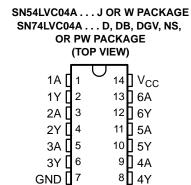
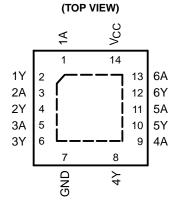


FEATURES

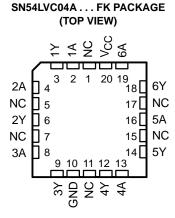
- Operate From 1.65 V to 3.6 V
- Specified From -40°C to 85°C, -40°C to 125°C, and -55°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t_{nd} of 4.5 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C

- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)





SN74LVC04A . . . RGY PACKAGE



NC - No internal connection

DESCRIPTION/ORDERING INFORMATION

The SN54LVC04A hex inverter contains six independent inverters designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC04A hex inverter contains six independent inverters designed for 1.65-V to 3.6-V V_{CC} operation. The 'LVC04A devices perform the Boolean function $Y = \overline{A}$.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION

T _A	PA	CKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	B5°C QFN – RGY Reel of 1000		SN74LVC04ARGYR	LC04A
		Tube of 50	SN74LVC04AD	
	SOIC - D	Reel of 2500	SN74LVC04ADR	LVC04A
-40°C to 125°C		Reel of 250	SN74LVC04ADT	
	SOP - NS	Reel of 2000	SN74LVC04ANSR	LVC04A
	SSOP - DB	Reel of 2000	SN74LVC04ADBR	LC04A
		Tube of 90	SN74LVC04APW	
	TSSOP - PW	Reel of 2000	SN74LVC04APWR	LC04A
		Reel of 250	SN74LVC04APWT	
	TVSOP - DGV	Reel of 2000	SN74LVC04ADGVR	LC04A
	CDIP – J	Tube of 25	SNJ54LVC04AJ	SNJ54LVC04AJ
-55°C to 125°C	CFP – W	Tube of 150	SNJ54LVC04AW	SNJ54LVC04AW
	LCCC - FK	Tube of 55	SNJ54LVC04AFK	SNJ54LVC04AFK

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH INVERTER)

INPUT A	OUTPUT Y
Н	Г
L	Н

LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)





Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V _{CC}	Supply voltage range		-0.5	6.5	V	
VI	Input voltage range (2)	Input voltage range ⁽²⁾		6.5	V	
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		-50	mA	
I _{OK}	Output clamp current	V _O < 0		-50	mA	
Io	Continuous output current			±50	mA	
	Continuous current through V _{CC} or GND	Continuous current through V _{CC} or GND			mA	
		D package ⁽⁴⁾		86		
		DB package ⁽⁴⁾		96	°C/W	
0	Dealeage the good impedance	DGV package ⁽⁴⁾		127		
θ_{JA}	Package thermal impedance	NS package ⁽⁴⁾		76		
		PW package ⁽⁴⁾		113		
		RGY package ⁽⁵⁾		47		
T _{stg}	Storage temperature range		-65	150	°C	
P _{tot}	Power dissipation	$T_A = -40$ °C to 125°C ⁽⁶⁾⁽⁷⁾		500	mW	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

The value of V_{CC} is provided in the recommended operating conditions table.

The package thermal impedance is calculated in accordance with JESD 51-7.

The package thermal impedance is calculated in accordance with JESD 51-5.

For the D package: above 70°C, the value of P_{tot} derates linearly with 8 mW/K. For the DB, DGV, NS, and PW packages: above 60°C, the value of P_{tot} derates linearly with 5.5 mW/K.



Recommended Operating Conditions⁽¹⁾

			SN54LV	C04A	
			–55°C to	125°C	UNIT
			MIN	MAX	
1/	Cumply voltage	Operating	2	3.6	V
V _{CC}	Supply voltage	Data retention only	1.5		V
V _{IH}	High-level input voltage	V _{CC} = 2.7 V to 3.6 V	2		V
V_{IL}	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	V
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V _{CC}	V
	High lavel autout august	V _{CC} = 2.7 V		-12	A
I _{OH}	High-level output current	$V_{CC} = 3 V$		-24	mA
1	Low lovel output ourrent	V _{CC} = 2.7 V		12	m Λ
I _{OL}	Low-level output current	V _{CC} = 3 V		24	mA

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

Recommended Operating Conditions (1)

					SN74L	VC04A			
			T _A =	25°C	-40°C	-40°C to 85°C		o 125°C	UNIT
			MIN	MAX	MIN	MAX	MIN	MIN MAX	
M	Cupply valtage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
V _{CC}	Supply voltage	Data retention only	1.5		1.5		1.5		V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		0.65 × V _{CC}		0.65 × V _{CC}		
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		1.7		1.7		V
	input voltage	V _{CC} = 2.7 V to 3.6 V	2		2		2		
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		0.35 × V _{CC}		0.35 × V _{CC}		0.35 × V _{CC}	
V_{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7		0.7		0.7	V
	input voltage	V _{CC} = 2.7 V to 3.6 V		0.8		0.8		0.8	
VI	Input voltage		0	5.5	0	5.5	0	5.5	V
Vo	Output voltage		0	V _{CC}	0	V _{CC}	0	V _{CC}	V
		V _{CC} = 1.65 V		-4		-4		-4	
	High-level	V _{CC} = 2.3 V		-8		-8		-8	0
I _{OH}	output current	V _{CC} = 2.7 V		-12		-12		-12	mA
		V _{CC} = 3 V		-24		-24		-24	
		V _{CC} = 1.65 V		4		4		4	
	Low-level	V _{CC} = 2.3 V		8		8		8	0
I _{OL}	output current	V _{CC} = 2.7 V		12		12		12	mA
		V _{CC} = 3 V		24		24		24	

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

			SN54LVC04A		
PARAMETER	TEST CONDITIONS	V _{cc}	–55°C to 125°C	UNIT	
			MIN MAX		
	$I_{OH} = -100 \mu A$	2.7 V to 3.6 V	V _{CC} - 0.2		
\/	L = 12 mA	2.7 V	2.2	V	
V_{OH}	$I_{OH} = -12 \text{ mA}$	3 V	2.4		
	$I_{OH} = -24 \text{ mA}$	3 V	2.2		
	I _{OL} = 100 μA	2.7 V to 3.6 V	0.2		
V _{OL}	I _{OL} = 12 mA	2.7 V	0.4	V	
	I _{OL} = 24 mA	3 V	0.55		
I _I	V _I = 5.5 V or GND	3.6 V	±5	μΑ	
I _{cc}	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	10	μΑ	
ΔI_{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	2.7 V to 3.6 V	500	μΑ	

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

					s	N74LVC04A	\			
PARAMETER	TEST CONDITIONS	v_{cc}	T _A = 25°C		–40°C to 85°C		–40°C to 125°C		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	$I_{OH} = -100 \mu A$	1.65 V to 3.6 V	V _{CC} - 0.2			V _{CC} - 0.2		$V_{CC} - 0.3$		
V _{OH}	$I_{OH} = -4 \text{ mA}$	1.65 V	1.29			1.2		1.05		
	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			1.7		1.55		V
	l – 12 mΔ	2.7 V	2.2			2.2		2.05		V
	$I_{OH} = -12 \text{ mA}$	3 V	2.4			2.4		2.25		
	$I_{OH} = -24 \text{ mA}$	3 V	2.3			2.2		2		
	I _{OL} = 100 μA	1.65 V to 3.6 V			0.1		0.2		0.3	V
	I _{OL} = 4 mA	1.65 V			0.24		0.45		0.6	
V _{OL}	$I_{OL} = 8 \text{ mA}$	2.3 V			0.3		0.7		0.85	
	I _{OL} = 12 mA	2.7 V			0.4		0.4		0.6	
	I _{OL} = 24 mA	3 V			0.55		0.55		8.0	
l _l	V _I = 5.5 V or GND	3.6 V			±1		±5		±20	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			1		10		40	μΑ
Δl _{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	2.7 V to 3.6 V			500		500		5000	μΑ
C _i	V _I = V _{CC} or GND	3.3 V		5						pF

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				SN54LVC	04A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{cc}	–55°C to 1	25°C	UNIT	
	(iidi 01)			MIN	MAX		
	۸	V	2.7 V		5.5		
^L pd	A	, r	3.3 V ± 0.3 V	0.5	4.5	ns	

SN54LVC04A, SN74LVC04A HEX INVERTERS

SCAS281R-JANUARY 1993-REVISED JULY 2005



Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

						S	N74LVC)4A			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{cc}	T,	= 25°C		–40°C to	85°C	–40°C to	125°C	UNIT
	(01)	(0011 01)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			1.8 V ± 0.15 V	1	4.1	7.5	1	8	1	9.5	
				2.5 V ± 0.2 V	1	3.6	7	1	7.5	1	9
^T pd	Α	T	2.7 V	1	3	5.3	1	5.5	1	7	ns
			3.3 V ± 0.3 V	1	2.5	4.3	1	4.5	1	6	
t _{sk(o)}			3.3 V ± 0.3 V					1		1.5	ns

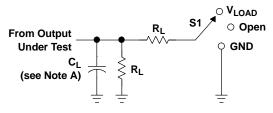
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{cc}	TYP	UNIT
			1.8 V	6	
C_{pd}	Power dissipation capacitance per gate	f = 10 MHz	2.5 V	7	
F-			3.3 V	8	



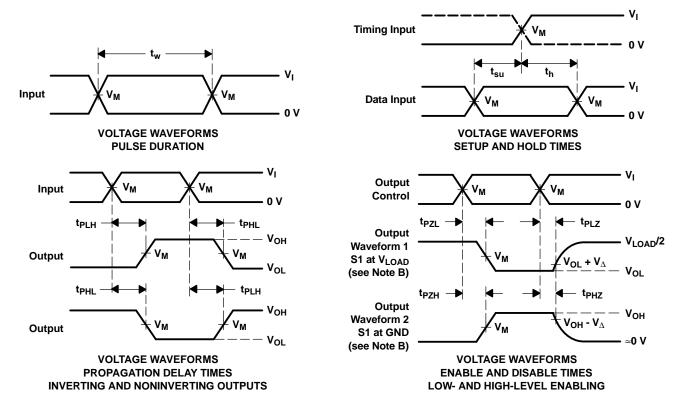
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL} t _{PLZ} /t _{PZL} t _{PHZ} /t _{PZH}	Open V _{LOAD} GND

LOAD CIRCUIT

.,	INF	PUTS	.,	.,		_	.,
V _{CC}	V _I	t _r /t _f	V _M	V _{LOAD}	CL	R _L	$oldsymbol{V}_\Delta$
1.8 V ± 0.15 V	v _{cc}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \ \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9760501Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
5962-9760501QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
5962-9760501QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN74LVC04AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI	Samples Not Available
SN74LVC04ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADGVRG4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	Request Free Samples
SN74LVC04ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ADTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LVC04ADTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	Samples Not Available
SN74LVC04APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04APWRG3	PREVIEW	TSSOP	PW	14	2000	TBD	Call TI	Call TI	Samples Not Available
SN74LVC04APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74LVC04APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74LVC04ARGYR	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Request Free Samples
SN74LVC04ARGYRG4	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Request Free Samples
SNJ54LVC04AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Contact TI Distributor or Sales Office
SNJ54LVC04AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Contact TI Distributor or Sales Office
SNJ54LVC04AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Contact TI Distributor or Sales Office

PACKAGE OPTION ADDENDUM



www.ti.com 7-Oct-2010

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54LVC04A, SN74LVC04A:

Catalog: SN74LVC04A

Automotive: SN74LVC04A-Q1, SN74LVC04A-Q1

■ Enhanced Product: SN74LVC04A-EP, SN74LVC04A-EP

Military: SN54LVC04A

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product





7-Oct-2010

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC04ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LVC04ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LVC04ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC04ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC04ADT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC04ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVC04APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC04APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC04ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC04ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LVC04ADGVR	TVSOP	DGV	14	2000	346.0	346.0	29.0
SN74LVC04ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LVC04ADR	SOIC	D	14	2500	333.2	345.9	28.6
SN74LVC04ADT	SOIC	D	14	250	346.0	346.0	33.0
SN74LVC04ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LVC04APWR	TSSOP	PW	14	2000	346.0	346.0	29.0
SN74LVC04APWT	TSSOP	PW	14	250	346.0	346.0	29.0
SN74LVC04ARGYR	VQFN	RGY	14	3000	346.0	346.0	29.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE

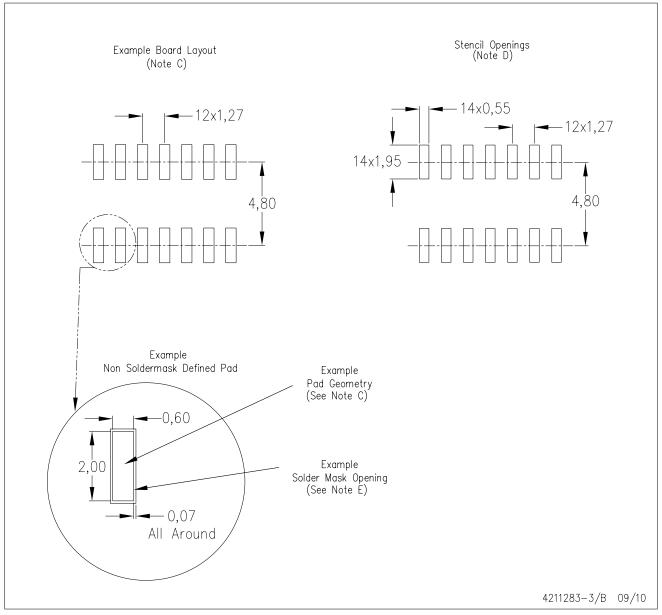


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



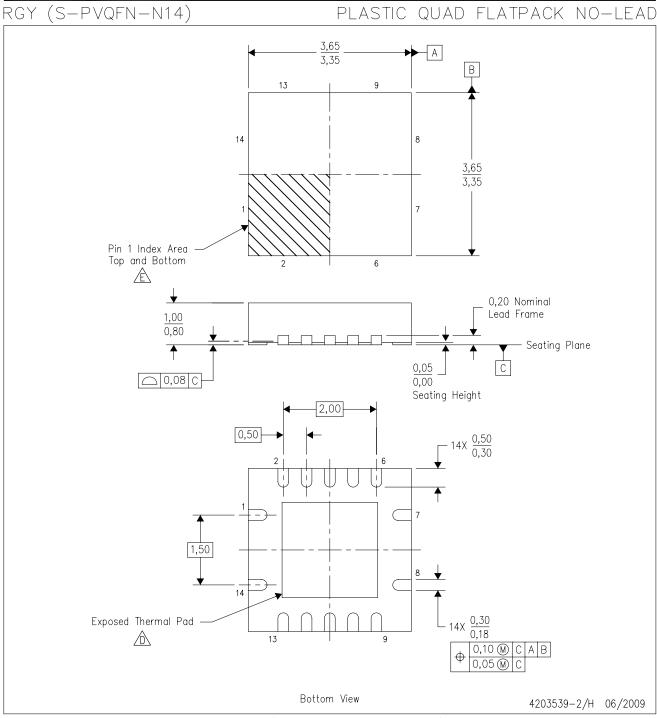
D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No—Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- F. Package complies to JEDEC MO-241 variation BA.

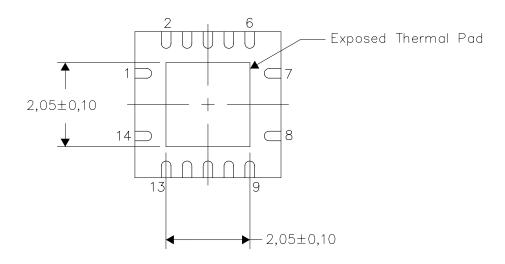


THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No—Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



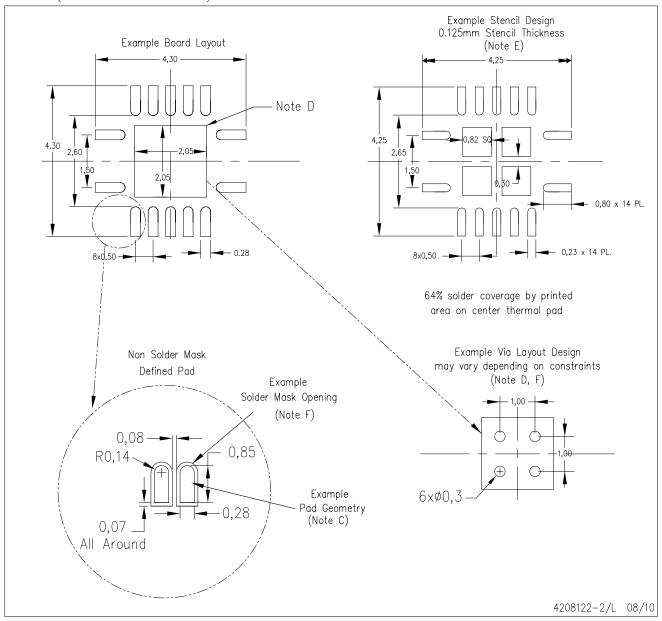
Bottom View

NOTES: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat—Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com http://www.ti.com.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

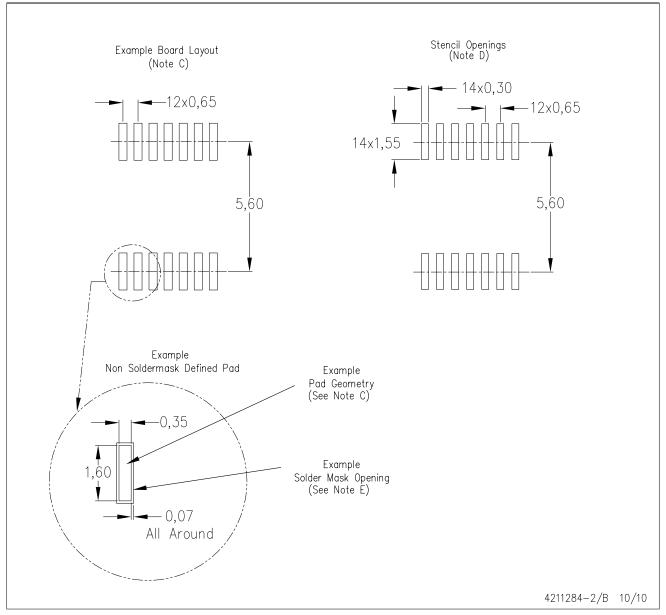
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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